

NOTES : TRIANGLE SYMBOLS IDENTIFY NOTES ON THIS DRAWING.

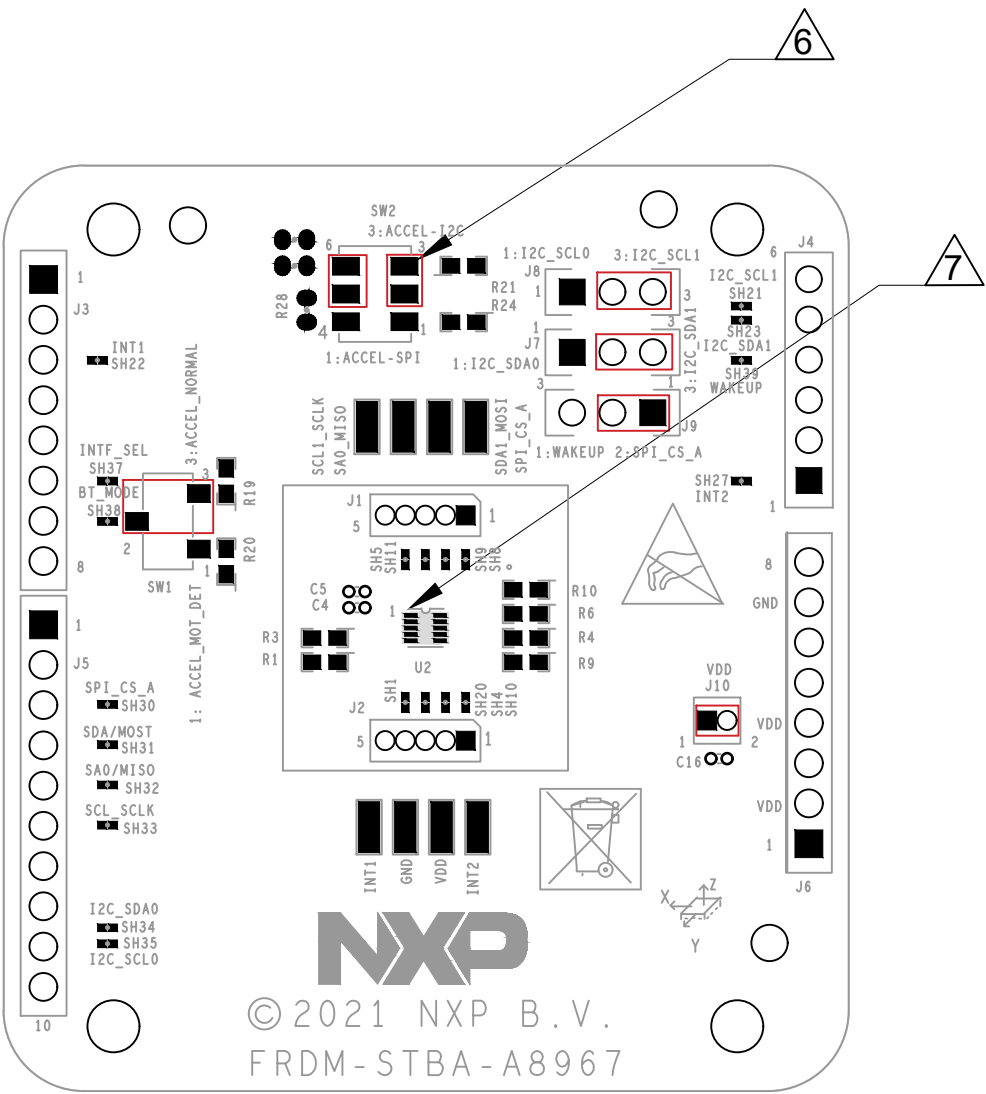
REVISIONS				
ZONE	REV	DESCRIPTION	DATE	APPROVED
	A	FIRST RELEASE	11/16/21	RICK

NOTES:

- ALL COMPONENTS MUST BE ABLE TO WITHSTAND THE Pb-FREE ASSEMBLY PROFILES DESCRIBED IN IPC/JEDEC J-STD-020C (LATEST VERSION)
- WORKMANSHIP SHALL CONFORM TO IPC-A-610 (LATEST REVISION) - CLASS 2 STANDARD.
- PART SUBSTITUTION CRITERIA : -
ALL COMPONENT SUBSTITUTIONS, INCLUDING PCB, MUST BE APPROVED AND DOCUMENTED BY NXP.
- MAXIMUM LEAD PROTRUSION ON PRIMARY AND SECONDARY SIDE OF PRINTED WIRING BOARD IS .070". EXCEPT J3-J6.
- IN CASES OF CONFLICT, ALL PLACEMENT LOCATIONS ARE TO BE GOVERNED BY THE X-Y CENTROID FILE, UNLESS EXPLICITLY STATED IN THIS ASSEMBLY DRAWING. SILKSCREEN REFERENCE DESIGNATORS ARE INCLUDED FOR CONVENIENCE ONLY.

△ SET BELOW FOR PCBA, BY USING 3PCS 211-79847 AND 1PCS 211-79323:
POSITION 1-2: J9,J10
POSITION 2-3: J7, J8, SW1
POSITION 2,3-5,6 : SW2

△ PAY ATTENTION TO U2 ASSEMBLY SINCE NO SOLDER-MASK UNDER IT.




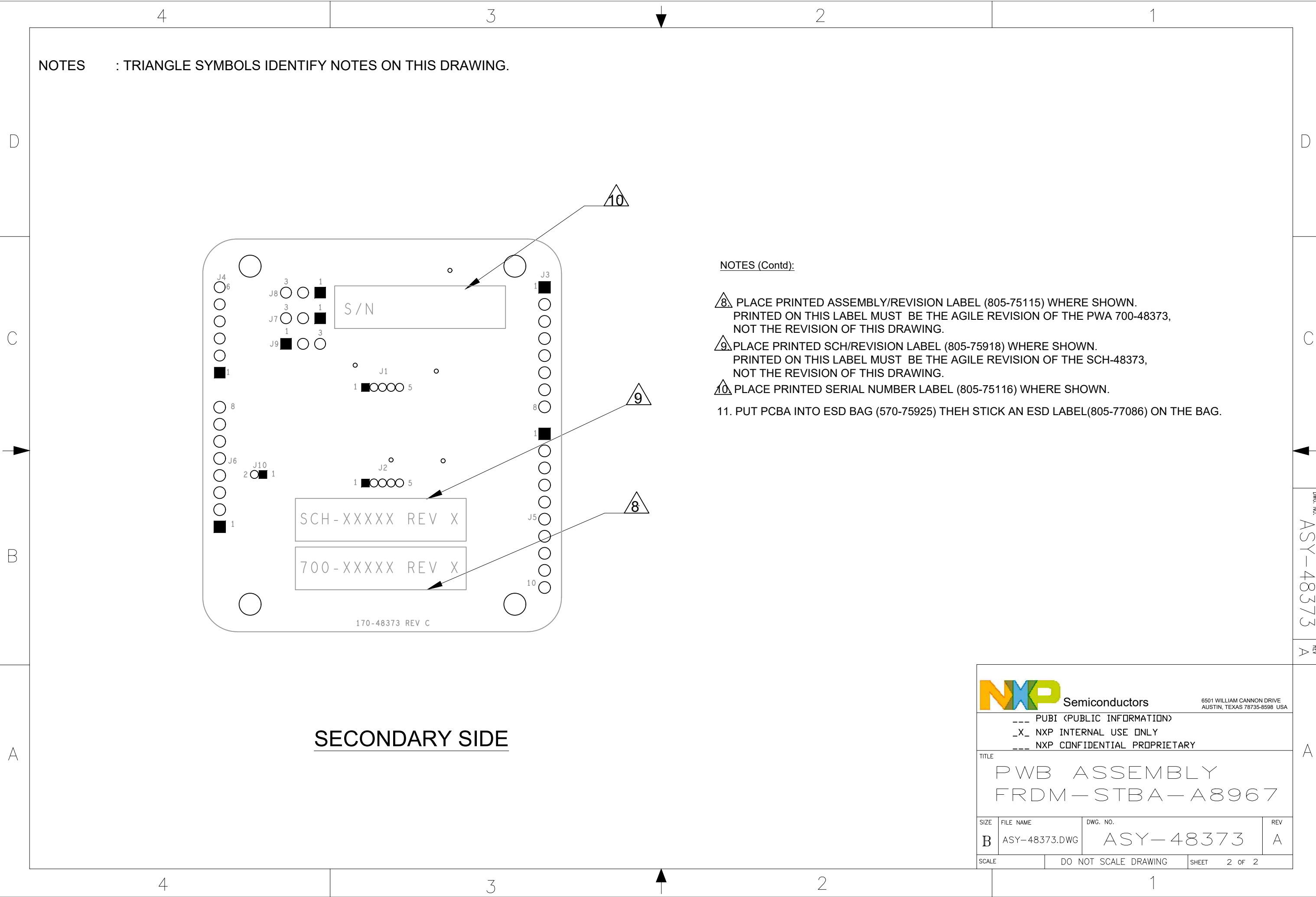
PRIMARY SIDE

RoHS : ALL PARTS, MATERIALS AND FINISHED ASSEMBLY SHALL MEET THE RoHS COMMISSION DELEGATED DIRECTIVE (EU) 2015 / 863 OF MARCH 31 2015 AMENDING ANNEX II TO DIRECTIVE 2011 / 65 / EU. A CERTIFICATE OF COMPLIANCE IS REQUIRED UPON REQUEST.

REACH : ALL PARTS, MATERIALS AND FINISHED ASSEMBLY SHALL NOT CONTAIN ANY OF THE SUBSTANCES OF VERY HIGH CONCERN (SVHC) ABOVE THE THRESHOLD VALUE PER THE CURRENT ECHA LIST OF SVHC'S, AND WITH THE ANNEX XIV OF REACH DIRECTIVE 76 / 769 / EEC.. A CERTIFICATE OF COMPLIANCE IS REQUIRED UPON REQUEST.

SOLDER PROCESS		
Pb FREE	<input checked="" type="checkbox"/> YES	<input type="checkbox"/> NO
NO-CLEAN	<input type="checkbox"/> YES	<input checked="" type="checkbox"/> NO

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. TOLERANCES ARE: DECIMALS .XX ±.020 .XXX ±.010 ✓ RMS ALL MACHINED SURFACES BREAK ALL SHARP EDGES AND CORNERS, REMOVE BURRS. UNDERLINED DIM. NOT TO SCALE. THIRD ANGLE ORTHOGRAPHIC PROJECTION IS USED.	PART NO. 700-48373		 Semiconductors 6501 WILLIAM CANNON DRIVE AUSTIN, TEXAS 78735-8598 USA			
	THIS DOCUMENT CONTAINS INFORMATION PROPRIETARY TO NXP AND SHALL NOT BE USED FOR ENGINEERING DESIGN, PROCUREMENT OR MANUFACTURE IN WHOLE OR IN PART WITHOUT THE CONSENT OF NXP.					
	--- PUBI (PUBLIC INFORMATION) --- X_ NXP INTERNAL USE ONLY --- NXP CONFIDENTIAL PROPRIETARY		TITLE PWB ASSEMBLY FRDM-STBA-A8967			
MATERIAL	APPROVALS		DATE		SIZE B FILE NAME ASY-48373.DWG DWG. NO. ASY-48373 REV A	
	DRAWN ROY	11/16/21				
FINISH	CHECKED ROSS	11/16/21				
HEAT TREAT	DESIGN ENGINEER RICK	11/16/21				
			SCALE		DO NOT SCALE DRAWING	
			SHEET		1 OF 2	




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NOTES (Contd):

8. PLACE PRINTED ASSEMBLY/REVISION LABEL (805-75115) WHERE SHOWN. PRINTED ON THIS LABEL MUST BE THE AGILE REVISION OF THE PWA 700-48373, NOT THE REVISION OF THIS DRAWING.
9. PLACE PRINTED SCH/REVISION LABEL (805-75918) WHERE SHOWN. PRINTED ON THIS LABEL MUST BE THE AGILE REVISION OF THE SCH-48373, NOT THE REVISION OF THIS DRAWING.
10. PLACE PRINTED SERIAL NUMBER LABEL (805-75116) WHERE SHOWN.
11. PUT PCBA INTO ESD BAG (570-75925) THEN STICK AN ESD LABEL(805-77086) ON THE BAG.

SECONDARY SIDE

 NXP Semiconductors 6501 WILLIAM CANNON DRIVE AUSTIN, TEXAS 78735-8598 USA			
--- PUBI <PUBLIC INFORMATION> _X_ NXP INTERNAL USE ONLY --- NXP CONFIDENTIAL PROPRIETARY			
TITLE PWB ASSEMBLY FRDM-STBA-A8967			
SIZE B	FILE NAME ASY-48373.DWG	DWG. NO. ASY-48373	REV A
SCALE	DO NOT SCALE DRAWING		SHEET 2 OF 2